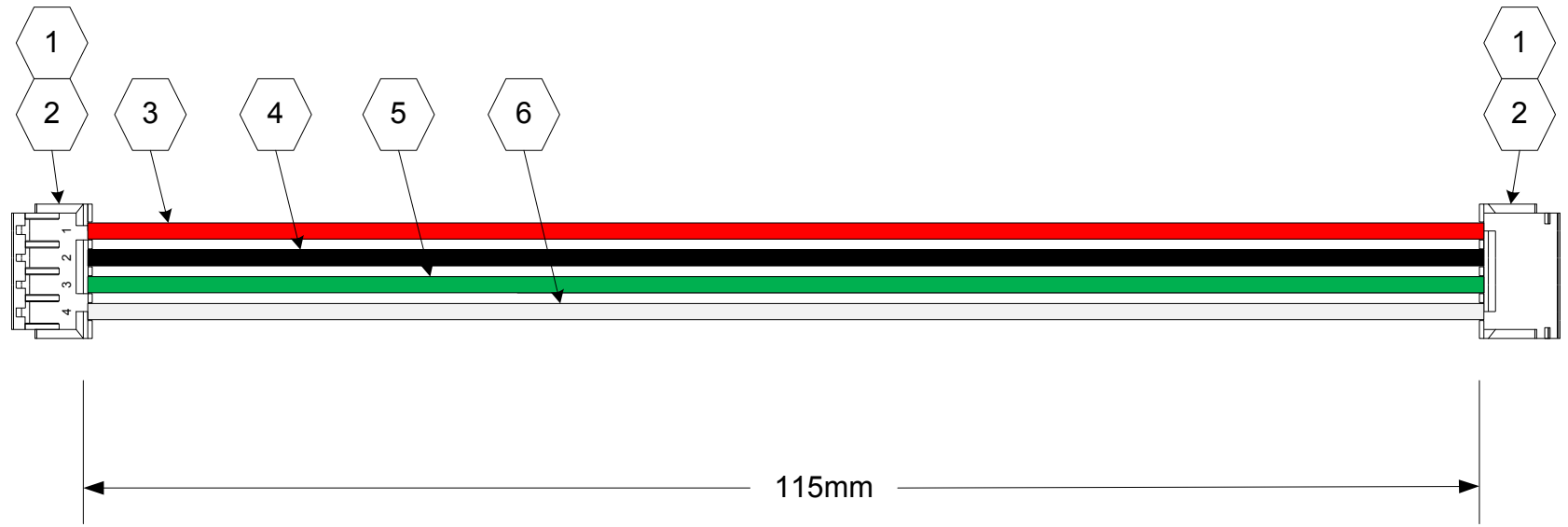


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												COMPUTER GENERATED DRAWING - DO NOT REVISE MANUALLY								
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												REV	DESCRIPTION		DATE		APPROVED			
												A	ECO# 2136368, Initial Release		01/29/22014		HPC			
												B	ECO# 2139950, REV B Release		02/01/2014		HPC			
												C	ECO# 2139951, REV C Release		02/17/2014		HPC			
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														ENGR	Eric Pruett		01/29/2014			
														APVD	Joe Siddall		01/29/2014			
														MFG				TITLE	NIRscan TEC Drive Thermistor Cable	
														GA	314 CP					
NEXT ASSY		USED ON						B	DRAWING NO	2513484		REV	C							
APPLICATION						SW	Microsoft® Office® Visio® 2007		SCALE	NONE		SHEET	1 of 3							



Quantity	Item	Part Number	Description	Manuf.
2	1	EHR-4	EH 4 Pin 2.5mm Connector Housing	JST
8	2	SEH-001T-P0.6	EH 22-30 AWG Crimp Pin	JST
1	3	1855/19 RD	Red 22 AWG PVC hook-up wire	Alpha
1	4	1855/19 BK	Black 22 AWG PVC hook-up wire	Alpha
1	5	1854/19 GR	Green 24 AWG PVC hook-up wire	Alpha
1	6	1854/19 WH	White 24 AWG PVC hook-up wire	Alpha

- NOTE:
- Wire may be substituted with wire that meets or exceeds the published specification of the wire listed.
 - Wire color choice is optional.

NIRscan TEC Cable

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<div>Revision History</div> <table><tr><td>A</td><td>ECO# 2136368, Initial Release</td></tr><tr><td>B</td><td>ECO# 2139950, REV B Release, Add cable length</td></tr><tr><td>C</td><td>ECO# 2139951, REV C Release, Up-date title block, Disclaimer</td></tr></table>																A	ECO# 2136368, Initial Release	B	ECO# 2139950, REV B Release, Add cable length	C	ECO# 2139951, REV C Release, Up-date title block, Disclaimer
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